

INERTIAL SENSOR: 3Axis - 2g/6g LINEAR ACCELEROMETER

FEATURES

- 2.4V TO 3.6V SINGLE SUPPLY OPERATION
- 0.5mg RESOLUTION OVER 100Hz BW
- 2g/6g USER SELECTABLE FULL-SCALE
- OUTPUT VOLTAGE, OFFSET AND SENSITIVITY RATIOMETRIC TO THE SUPPLY VOLTAGE
- FACTORY TRIMMED DEVICE SENSITIVITY AND OFFSET
- EMBEDDED SELF TEST
- **HIGH SHOCK SURVIVABILITY**

2 **DESCRIPTION**

The LIS3L02AQ is a low-power three-axis linear accelerometer that includes a sensing element and an IC interface able to take the information from the sensing element and to provide an analog signal to the external world.

The sensing element, capable to detect the acceleration, is manufactured using a dedicated process called THELMA (Thick Epi-Poly Layer for Microactuators and Accelerometers) developed by ST to produce inertial sensors and actuators in silicon.

The IC interface instead is manufactured 'siny' a CMOS process that allows high level of in earta ion to design a dedicated circuit which is trin med to better match the sensing element characteristics.

Figure 1. Package

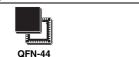


Table 1. Order Codes

Figure 1. Package QFN Table 1. Order Codes	-44	200lucit(s)
Part Number	Package	400
LIS3L02AQ	QFN-44	X VOVI
	4.4	

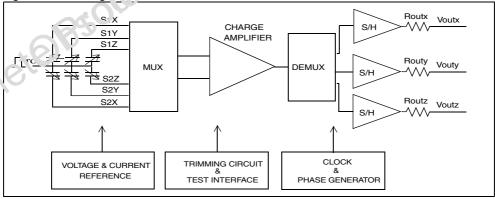
The LIS3L02AQ has a user selectal to the scale of 2g, 6g and it is capable of measuring receierations over a maximum bandwidth of 4.0 KH, for the X and Y axis and 2.5KHz for the 7 xis. The device bandwidth may be reduce a by u in g external capacitances. A self-test cap ab it, a ows the user to check the functioning of the system.

The LIS3I Oz No is available in plastic SMD package and it is main ed over a temperature range extending ໂປ. ເປັນ C to +85°C.

The LiS3L02AQ belongs to a family of products suitbie for a variety of applications:

- Motion activated functions in mobile terminals
- Gaming and Virtual Reality input devices
- Free-fall detection and Data protection
- Antitheft systems and Inertial Navigation
- Appliance Control and Robotics

Figure 2. Block Diagonal



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Table 2. Pin Description

N°	Pin	Function	
1 to 3	NC	Internally not connected	
4	GND	0V supply	
5	Vdd	Power supply	
6	Vouty	Output Voltage	
7	ST	Self Test (Logic 0: normal mode; Logic 1: Self-test)	.16
8	Voutx	Output Voltage	apduct(s)
9-13	NC	Internally not connected	41/10
14	PD	Power Down (Logic 0: normal mode; Logic 1: Power-Down mode)	200,0
15	Voutz	Output Voltage	331
16	FS	Full Scale selection (Logic 0: 2g Full-scale; Logic 1: 6g Full-scale)	
17-18	Reserved	Leave unconnected	
19	NC	Internally not connected	
20	Reserved	Leave unconnected	
21	NC	Internally not connected	
22-23	Reserved	Leave unconnected	
24-25	NC	Internally not connected	
26	Reserved	Connect to Vdd or GND	
27	Reserved	Leave unconnected or connect to V.'d	
28	Reserved	Leave unconnected or cor nec. to GND	
29-44	NC	Internally not so, nested	

Figure 3. Pin Connection (Tc o view)

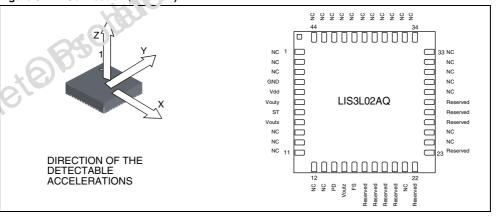


Table 3. Electrical Characteristics

(Temperature range -40°C to +85°C) All the parameters are specified @ Vdd =3.3V, T=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ. ¹	Max.	Unit
Vdd	Supply voltage		2.4	3.3	3.6	٧
ldd	Supply current	mean value PD pin connected to GND		0.85	1.5	mA
IddPdn	Supply current in Power Down Mode	rms value PD pin connected to Vdd		2	5	μΑ
Voff	Zero-g level ²	T = 25°C	Vdd/2-10%	Vdd/2	Vdd/2+10%	٧
OffDr	Zero-g level Vs temperature	Delta from +25°C		±1.5		mg/°C
Ar	Acceleration range ³	FS pin connected to GND	±1.8	±2.0		g
		FS pin connected to Vdd	±5.4	±6.0		9
So	Sensitivity ²	Full-scale = 2g	Vdd/5-10%	Vdd/5	Yud/5+10%	V/g
		Full-scale = 6g	Vdd/15-10%	Vdc <u>.</u> /15	'au/15+10%	V/g
SoDr	Sensitivity drift Vs temperature	Delta from +25°C	۵.0	± \.01	,	%/°C
NL	Non Linearity ⁴	Best fit straight line Full-scale = 2g X, Y axis	459	±0.3	±1.5	% FS
	ad a	Best fit straight line; Full-scale = 20, Z aris		±0.6	±2	% FS
CrossAx	Cross-Axis ⁵	951		±2	±4	%
fuc	Sensing Element Roso 12.1t	X, Y axis	3.2	4.0	4.8	KHz
	Frequency ⁶	Z axis	1.8	2.5	3.2	KHz
an	Acceleration noise density	Vdd=3.3V; Full-scale = 2g		50		μg/ √Hz
Vt	Vt S eli rest output voltage delta change 7,8,9	T = 25°C Vdd=3.3V Full-scale = 2g X axis	-20	-40		mV
~		T = 25°C Vdd=3.3V Full-scale = 2g Y axis	20	40		mV
		T = 25°C Vdd=3.3V Full-scale = 2g Z axis	20	50		mV

Table 3. Electrical Characteristics (continued)

(Temperature range -40°C to +85°C) All the parameters are specified @ Vdd =3.3V, T=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ. ¹	Max.	Unit	
Vst	Self test input	Logic 0 level	0		0.8	V	
		Logic 1 level	2.2		Vdd	V	
Rout	Output impedance		80	110	140	kΩ	
Cload	Capacitive load drive ¹⁰		320			pF	*(5)
Ton	Ton Turn-On Time at exit from Power Down mode Cload in μF 550*Cload +0.3						AUCIC
3. G 4. G 5. C 6. G 7. S 8. S 9. W 10.B	iffset and sensitivity are essentially re uaranteed by wafer level test and me uaranteed by design through measu ontribution to the measuring output ouaranteed by design elf test "output voltage delta change" elf test "output voltage delta change" /hen full-scale is set to 6g, self-test "oandwidth=1/(2"π*110KΩ*Cload)	easurement of initial offse rements done up to 1g of the inclination/accelerat is defined as Vout(vst=Lor varies cubically with supp	t and sensitivity ion along the perposicol gic1)-Vout(Vst=Logical oly voltage	0)	350th	jei	
	TE MAXIMUM RATING		LO				
Stresses :	above those listed as "absolu	te maximum ratinos	may caus a r	ermanent dan	nage to the de	vice This	<u>.</u>

- Notes: 1. Typical specifications are not guaranteed
 2. Offset and sensitivity are essentially ratiometric to supply voltage
 3. Guaranteed by wafer level test and measurement of initial offset and sensitivity

 - 4. Guaranteed by design through measurements done up to 1g
 5. Contribution to the measuring output of the inclination/acceleration along the perpendicular axis

 - Self test "output voltage delta change" is defined as Vout_(Vst=Logict)-Vout_(Vst=Logict)-Vout_(Vst=Logict)
 Self test "output voltage delta change" varies cubically with supply voltage
 When full-scale is set to 6g, self-test "output delta change" is one third of the specified value
 - 10.Bandwidth=1/($2^*\pi^*110K\Omega^*Cload$)

ABSOLUTE MAXIMUM RATING

Stresses above those listed as "absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device of these conditions is not implied. Exposure to maximum rating conditions for extended periods may after device reliability.

Table 4. Absolute Maximum Rating

Symbol	R iti. gs	Maximum Value	Unit
Vdd	Supply voltage	-0.3 to 7	V
Vin	Input voltage ca. ac. / control pin (FS, PD, ST)	-0.3 to Vdd +0.3	V
A _{POW}	Acceleration 'Arry axis, Powered, Vdd=3.3V)	3000g for 0.5 ms	
	25	10000g for 0.1 ms	
AU VP	Coeleration (Any axis, Unpowered)	3000g for 0.5 ms	
2/10		10000g for 0.1 ms	
T _{OP}	Operating Temperature Range	-40 to +85	°C
T _{STG}	Storage Temperature Range	-40 to +105	°C
ESD	Electrostatic discharge protection	2KV HBM	

FUNCTIONALITY

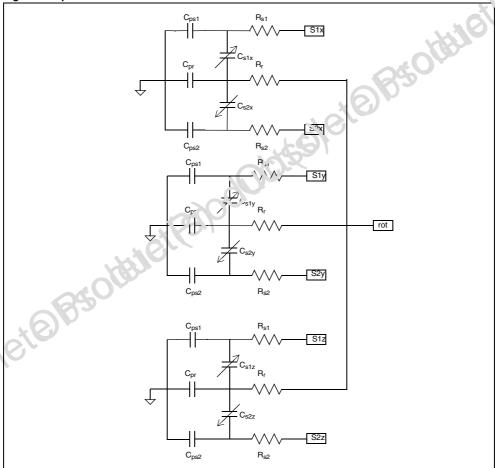
The LIS3L02AQ is a low-cost, low-power, analog output three-axis linear accelerometer packaged in QFN package. The complete device includes a sensing element and an IC interface able to take the information from the sensing element and to provide an analog signal to the external world.

3.1 Sensing element

The THELMA process is utilized to create a surface micro-machined accelerometer. The technology allows to (Sipolucile) carry out suspended silicon structures which are attached to the substrate in a few points called anchors and free to move on a plane parallel to the substrate itself. To be compatible with the traditional packaging techniques a cap is placed on top of the sensing element to avoid blocking the moving parts during the molding

The equivalent circuit for the sensing element is shown in the figure below; when a linear acceleration is applied, the proof mass displaces from its nominal position, causing an imbalance in the capacitive half-bridge. This imbalance is measured using charge integration in response to a voltage pulse applied to the sense capacitor.

Figure 4. Equivalent electrical circuit



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The nominal value of the capacitors, at steady state, is few pF and when an acceleration is applied the maximum variation of the capacitive load is few hundredths of pF.

3.2 IC Interface

The complete signal processing uses a fully differential structure, while the final stage converts the differential signal into a single-ended one to be compatible with the external world.

The first stage is a low-noise capacitive amplifier that implements a Correlated Double Sampling (CDS) at its output to cancel the offset and the 1/f noise. The produced signal is then sent to three different S&Hs, one for each channel, and made available to the outside.

EXPOUNCTION The low noise input amplifier operates at 200 kHz while the three S&Hs operate at a sampling frequency of 66 kHz. This allows a large oversampling ratio, which leads to in-band noise reduction and to an accurate output waveform.

All the analog parameters (output offset voltage and sensitivity) are ratiometric to the voltage supply. Increasing or decreasing the voltage supply, the sensitivity and the offset will increase or decrease linearly. The feature provides the cancellation of the error related to the voltage supply along an analog to digital conversion chain.

3.3 Factory calibration

The IC interface is factory calibrated to provide to the final user a device ready to operate.

The trimming values are stored inside the device by a non volatile structure. Any time the device is turned on, obsolete Brothitet Rapidolitical the trimming parameters are downloaded into the registers to be employed during the normal prelation thus

4 PACKAGE INFORMATION

Figure 5. QFN-44 Mechanical Data & Package Dimensions

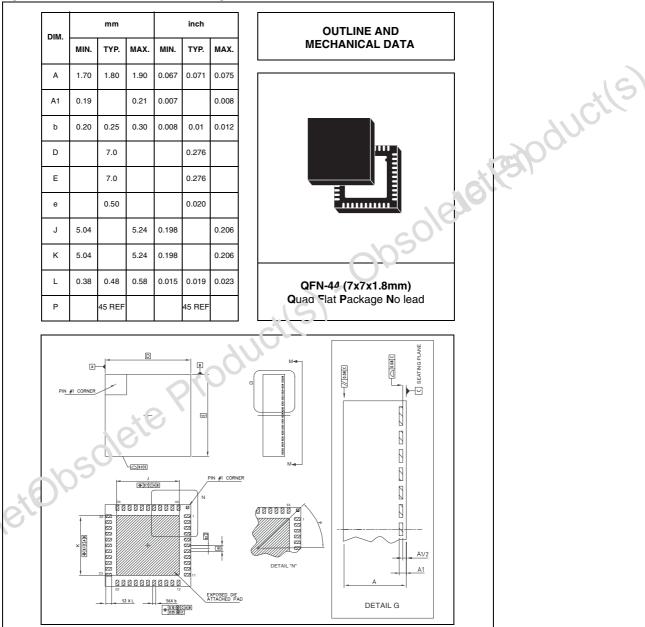


Table 5. Revision History

Date	Revision	Description of Changes
January 2004	1	First Issue
February 2004	2	Values of some parameters has been changed in Electrical characteristics table.
November 2004	3	Modified/added some values in the table 2 Electrical characteristics.
November 2004	4	Corrected few typo errors.

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